

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



IGBT

FGAF40N60UFD

Ultrafast IGBT

General Description

Fairchild's UFD series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses. The UFD series is designed for applications such as motor control and general inverters where high speed switching is a required feature.

Features

- · High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.3 \text{ V} @ I_C = 20 \text{A}$
- · High input impedance
- CO-PAK, IGBT with FRD : t_{rr} = 50ns (typ.)

Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





GCE

Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		FGAF40N60UFD	Units
V _{CES}	Collector-Emitter Voltage		600	V
V _{GES}	Gate-Emitter Voltage		± 20	V
	Collector Current	@ T _C = 25°C	40	Α
IC	Collector Current	@ T _C = 100°C	20	Α
I _{CM (1)}	Pulsed Collector Current		160	Α
l _F	Diode Continuous Forward Current	@ T _C = 100°C	15	Α
I _{FM}	Diode Maximum Forward Current	-	160	Α
P_{D}	Maximum Power Dissipation	@ $T_C = 25^{\circ}C$	100	W
	Maximum Power Dissipation	@ T _C = 100°C	40	W
TJ	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds		300	°C

Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

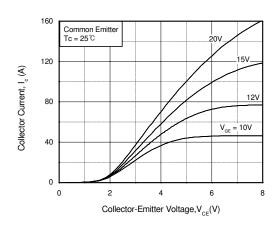
Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		1.2	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		2.6	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chai	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			٧
$\Delta B_{VCES}/$ ΔT_J	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0V, I _C = 1mA		0.6		V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	acteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 20$ mA, $V_{CE} = V_{GE}$	3.5	5.1	6.5	V
	Collector to Emitter	$I_{\rm C} = 20A$, $V_{\rm GE} = 15V$		2.3	3.0	V
$V_{CE(sat)}$	Saturation Voltage	$I_{C} = 40A$, $V_{GE} = 15V$		3.1		V
	Characteristics		Ti-		1	
C _{ies}	Input Capacitance	$V_{CE} = 30V_{CE} = 0V_{CE}$		1075		pF
C _{oes}	Output Capacitance	f = 1MHz		170		pF
C _{res}	Reverse Transfer Capacitance			50		pF
Switchir	ng Characteristics					
t _{d(on)}	Turn-On Delay Time			15		ns
t _r	Rise Time			30		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 20\text{A},$		65	130	ns
t _f	Fall Time	$R_G = 10\Omega, V_{GE} = 15V,$		35	100	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		470		uJ
E _{off}	Turn-Off Switching Loss			130		uJ
E _{ts}	Total Switching Loss			600	1000	uJ
t _{d(on)}	Turn-On Delay Time			30		ns
t _r	Rise Time			37		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 20 \text{A},$		110	200	ns
t _f	Fall Time	$R_G = 10\Omega, V_{GE} = 15V,$		80	250	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C		500		uJ
E _{off}	Turn-Off Switching Loss			310		uJ
E _{ts}	Total Switching Loss]		810	1200	uJ
Q_g	Total Gate Charge	V - 300 V I - 30A		77	150	nC
Q _{ge}	Gate-Emitter Charge	$V_{CE} = 300 \text{ V}, I_{C} = 20\text{A},$ $V_{GF} = 15\text{V}$		20	30	nC
Q _{gc}	Gate-Collector Charge	VGE - 13V		25	40	nC
	Internal Emitter Inductance	Measured 5mm from PKG		14		nH

Electrical Characteristics of DIODE $T_{C} = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
V	Diode Forward Voltage	I _F = 15A	$T_C = 25^{\circ}C$		1.4	1.7	V
V_{FM}			T _C = 100°C		1.3		
	Diode Reverse Recovery Time		T _C = 25°C		50	95	ne
t _{rr}		I _F = 15A,	T _C = 100°C		74		ns
	Diode Peak Reverse Recovery		$T_C = 25^{\circ}C$		4.5	6.0	Α
^I rr	Current	di/dt = 200A/us	T _C = 100°C		6.5		
	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$		80	180	nC
Q_{rr}			T _C = 100°C		220		110



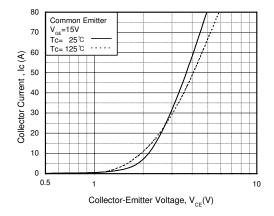
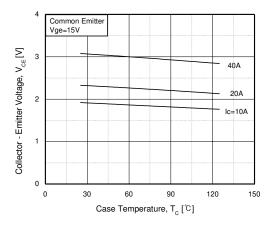


Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



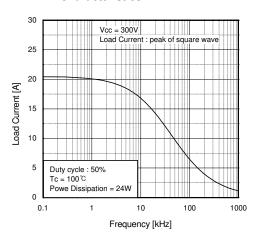
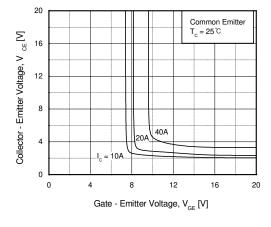


Fig 3. Saturation Voltage vs.

Case Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency



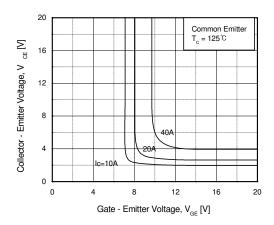
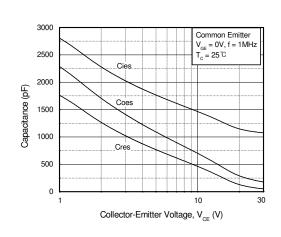


Fig 5. Saturation Voltage vs. V_{GE}

Fig 6. Saturation Voltage vs. $V_{\rm GE}$

©2004 Fairchild Semiconductor Corporation



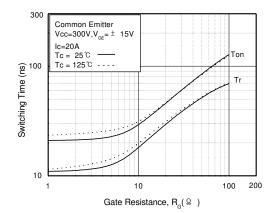
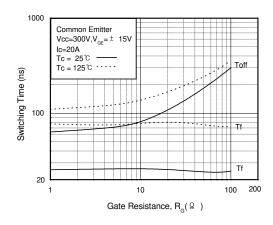


Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



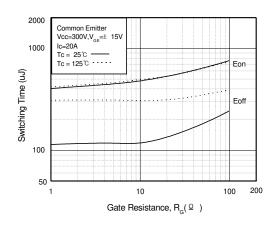
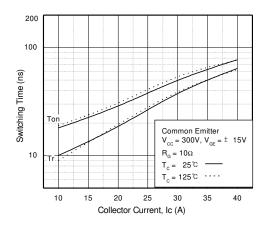


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



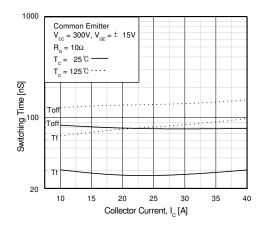
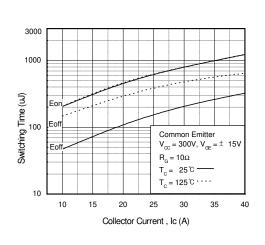


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



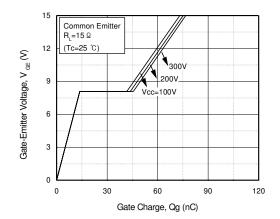
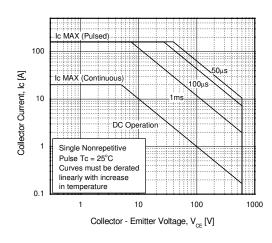


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



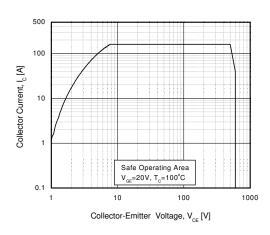


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

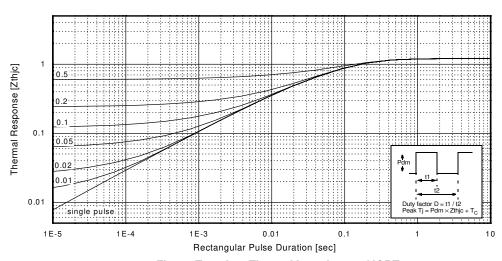
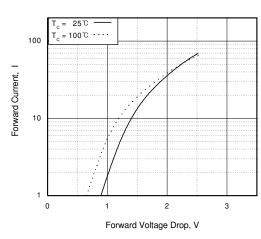


Fig 17. Transient Thermal Impedance of IGBT



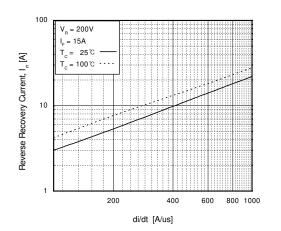
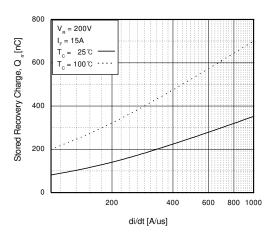


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



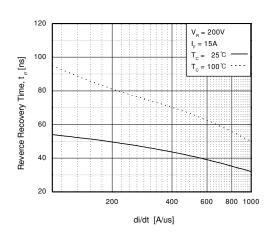
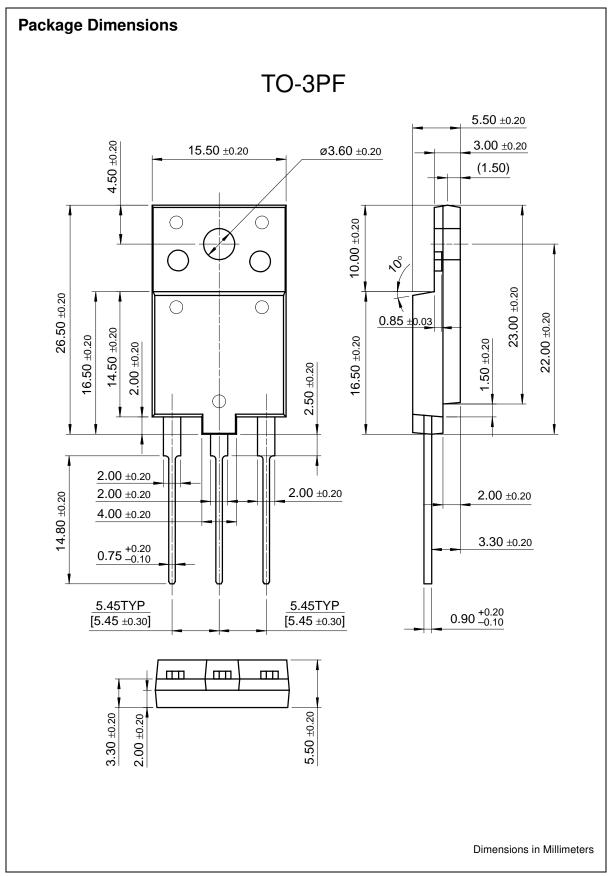


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time



TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	FACT Quiet Series™	ISOPLANAR™	POP^{TM}	Stealth™
ActiveArray™	FAST [®]	LittleFET™	Power247™	SuperFET™
Bottomless™	FASTr™	MICROCOUPLER™	PowerSaver™	SuperSOT™-3
CoolFET™	FPS™	MicroFET™	PowerTrench [®]	SuperSOT™-6
CROSSVOLT™	FRFET™	MicroPak™	QFET [®]	SuperSOT™-8
DOME™	GlobalOptoisolator™	MICROWIRE™	QS TM	SyncFET™
EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic [®]
E ² CMOS™	HiSeC™	MSXPro™	Quiet Series™	TINYOPTO™
EnSigna™	I ² C TM	OCXTM	RapidConfigure™	TruTranslation™
FACT™	ImpliedDisconnect™	OCXPro™	RapidConnect™	UHC™
Across the board. Around the world.™		OPTOLOGIC [®]	SILENT SWITCHER®	UltraFET [®]
The Power Franchise™		OPTOPLANAR™	SMART START™	VCX™
Programmable Active Droop™		PACMAN™	SPM™	

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS. NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative